

3.0SMC Series



Uni-directional



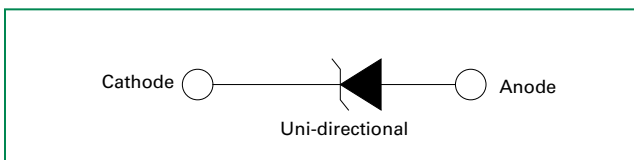
Maximum Ratings and Thermal Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Power Dissipation on Infinite Heat Sink at $T_L=50^\circ\text{C}$	P_D	6.5	W
Peak Forward Surge Current, 8.3ms Single Half Sine Wave (Note 1)	I_{FSM}	300	A
Maximum Instantaneous Forward Voltage at 100A for Unidirectional Only	V_F	3.5	V
Operating Temperature Range	T_J	-65 to 150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-65 to 175	$^\circ\text{C}$
Typical Thermal Resistance Junction to Lead	$R_{\theta JL}$	15	$^\circ\text{C/W}$
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	75	$^\circ\text{C/W}$

Notes:

1. Measured on 8.3ms single half sine wave or equivalent square wave for unidirectional device only, duty cycle=4 per minute maximum.

Functional Diagram



Additional Information



Datasheet



Resources



Samples

Description

The 3.0SMC series is designed specifically to protect sensitive electronic equipment from voltage transients induced by lightning and other transient voltage events.

Features

- For surface mounted applications in order to optimize board space
- Low profile package
- Typical failure mode is short from over-specified voltage or current
- Whisker test is conducted based on JEDEC JESD201A per its table 4a and 4c
- IEC-61000-4-2 ESD 30kV(Air), 30kV (Contact)
- I_{PP} is specified @ 8/20 μs surge waveform
- Built-in strain relief
- $V_{BR} @ T_J = V_{BR} @ 25^\circ\text{C} \times (1 + \alpha T \times (T_J - 25))$ (α : Temperature Coefficient, typical value is 0.1%)
- Glass passivated chip junction
- Fast response time: typically less than 1.0ps from 0V to BV min
- Excellent clamping capability
- Low incremental surge resistance
- High temperature to reflow soldering guaranteed: 260 $^\circ\text{C}/40\text{sec}$
- Meet MSL level1, per J-STD-020, LF maximum peak of 260 $^\circ\text{C}$
- Matte tin lead-free plated
- Halogen free and RoHS compliant
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)

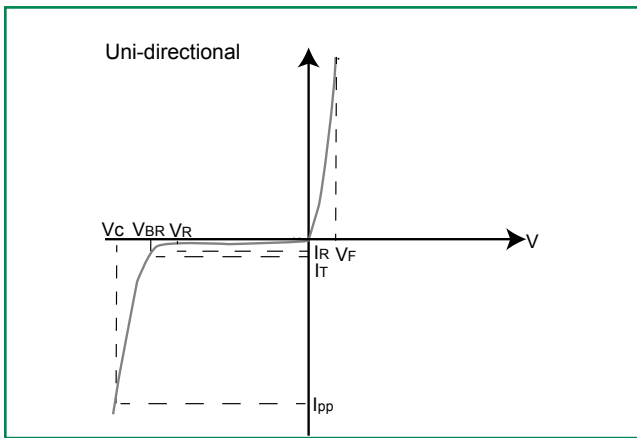
Applications

TVS devices are ideal for the protection of I/O Interfaces, V_{CC} bus and other vulnerable circuits used in Telecom, Computer, Industrial and Consumer electronic applications.

Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Part Number (Uni)	Marking	Reverse Stand off Voltage V_R (Volts)	Breakdown Voltage V_{BR} (Volts) @ I_T		Test Current I_T (mA)	Maximum Clamping Voltage V_C @ $8/20\mu\text{S}$ I_{pp} (V)	Maximum Peak Pulse Current I_{pp} @ $8/20\mu\text{S}$ (A)	Maximum Reverse Leakage I_R @ V_R (μA)
			MIN	MAX				
3.0SMC20A	YLA	20.0	22.20	24.50	1	42	570	1
3.0SMC24A	YLC	24.0	26.70	29.50	1	51	520	1
3.0SMC28A	YLE	28.0	31.10	34.40	1	59	470	1
3.0SMC30A	YLF	30.0	33.30	36.80	1	62	420	1
3.0SMC33A	YLG	33.0	36.70	40.60	1	70	365	1

I-V Curve Characteristics



- P_{PPM} Peak Pulse Power Dissipation** – Max power dissipation
- V_R Stand-off Voltage** – Maximum voltage that can be applied to the TVS without operation
- V_{BR} Breakdown Voltage** – Maximum voltage that flows through the TVS at a specified test current (I_T)
- V_C Clamping Voltage** – Peak voltage measured across the TVS at a specified I_{ppm} (peak impulse current)
- I_R Reverse Leakage Current** – Current measured at V_R
- V_F Forward Voltage Drop for Uni-directional**

Ratings and Characteristic Curves ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Figure 1 - TVS Transients Clamping Waveform

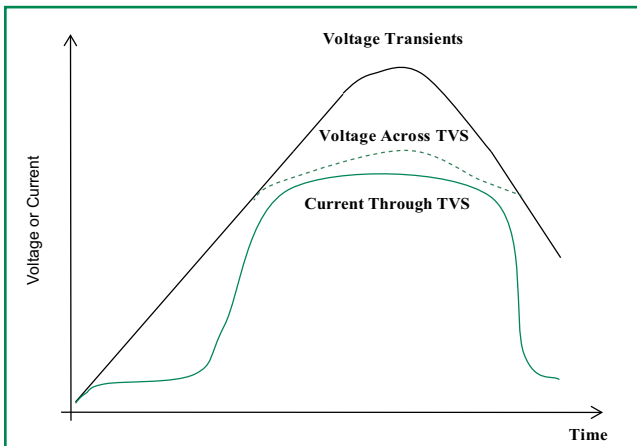
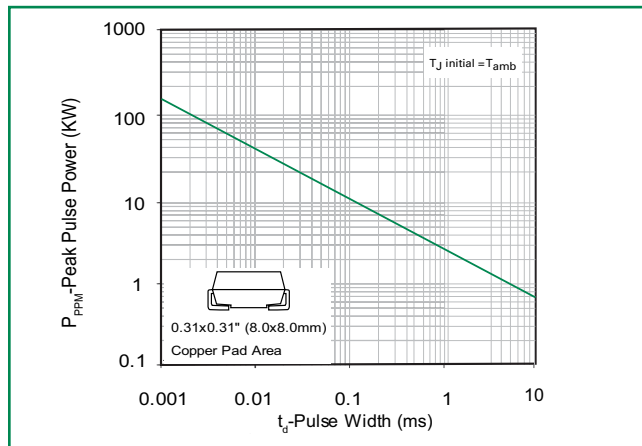


Figure 2 - Peak Pulse Power Rating



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Ratings and Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted) (Continued)

Figure 3 - Peak Pulse Power Derating Curve

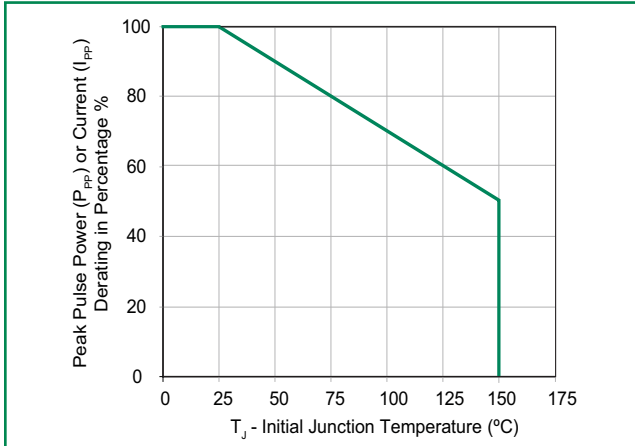


Figure 4 - Pulse Waveform

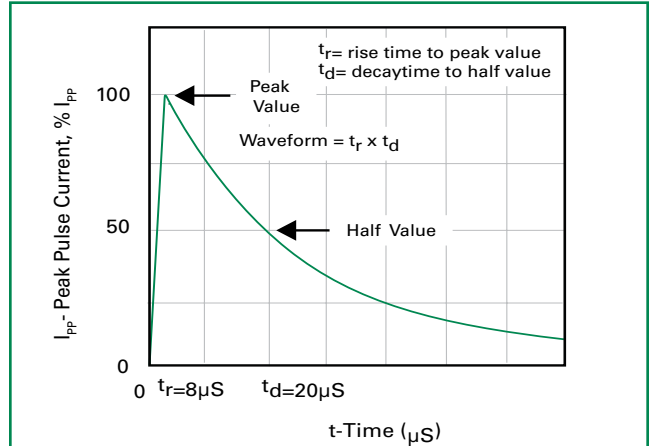


Figure 5 - Typical Junction Capacitance

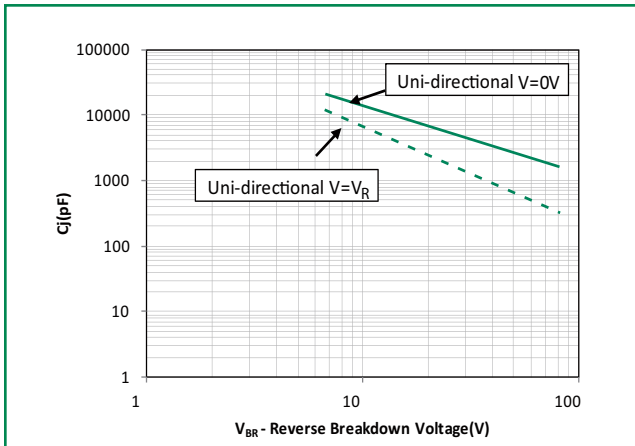


Figure 6 - Typical Transient Thermal Impedance

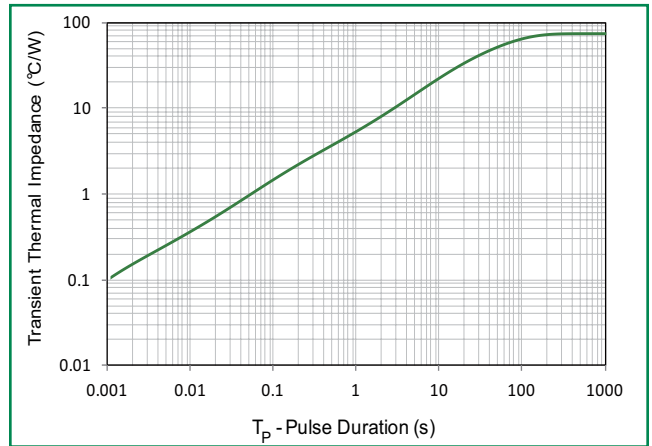


Figure 7 - Maximum Non-Repetitive Peak Forward Surge Current Uni-Directional only

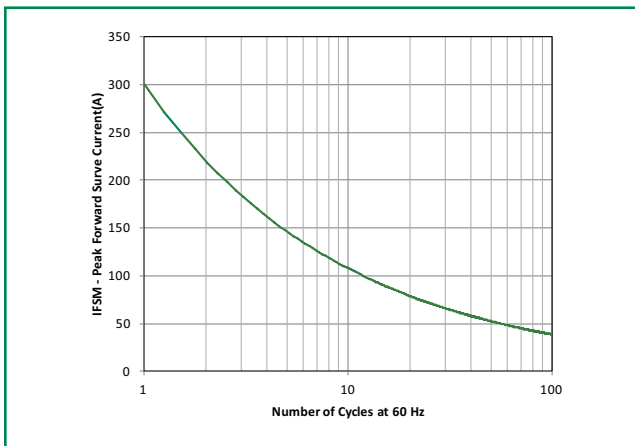
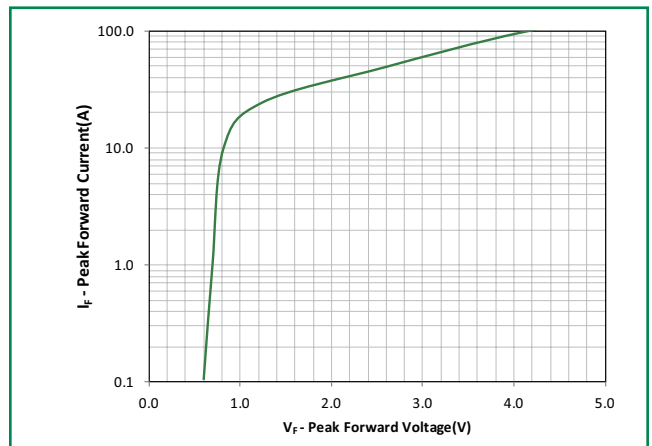
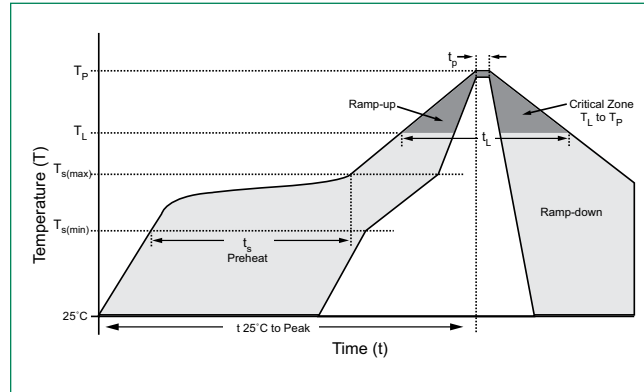


Figure 8 - Peak Forward Voltage Drop vs Peak Forward Current (Typical Values)



Soldering Parameters

Reflow Condition		Lead-free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_A) to peak)		3°C/second max
$T_{s(max)}$ to T_A - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_A) (Liquidus)	217°C
	- Time (min to max) (t_s)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



Physical Specifications

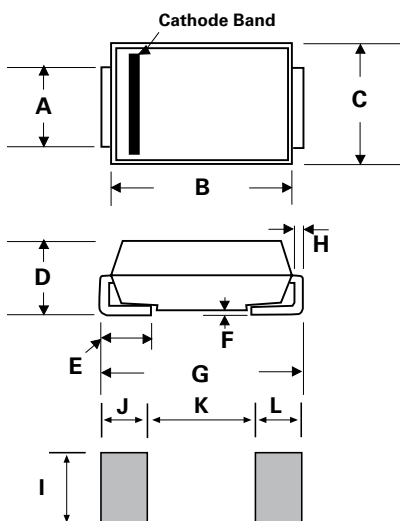
Weight	0.007 ounce, 0.21 grams
Case	JEDEC DO214AB. Molded plastic body over glass passivated junction
Polarity	Color band denotes positive end (cathode) except Bidirectional.
Terminal	Matte Tin-plated leads, Solderable per JESD22-B102

Environmental Specifications

High Temp. Storage	JESD22-A103
HTRB	JESD22-A108
Temperature Cycling	JESD22-A104
MSL	JEDEC-J-STD-020, Level 1
H3TRB	JESD22-A101
RSH	JESD22-A111

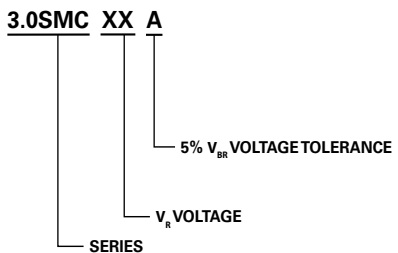
Dimensions

DO-214AB (SMC J-Bend)

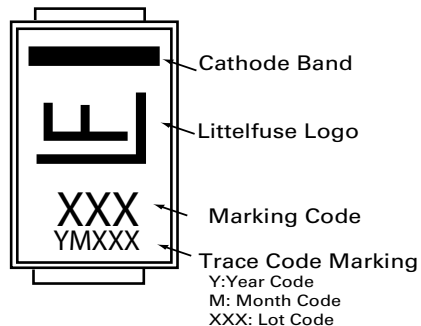


Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.114	0.126	2.900	3.200
B	0.260	0.280	6.600	7.110
C	0.220	0.245	5.590	6.220
D	0.079	0.103	2.060	2.620
E	0.030	0.060	0.760	1.520
F	-	0.008	-	0.203
G	0.305	0.320	7.750	8.130
H	0.006	0.012	0.152	0.305
I	0.129	-	3.300	-
J	0.094	-	2.400	-
K	-	0.165	-	4.200
L	0.094	-	2.400	-

Part Numbering System



Part Marking System



Packaging Options

Part number	Component Package	Quantity	Packaging Option	Packaging Specification
3.0SMCxxX	DO-214AB	3000	Tape & Reel - 16mm tape/13" reel	EIA STD RS-481

Tape and Reel Specification

